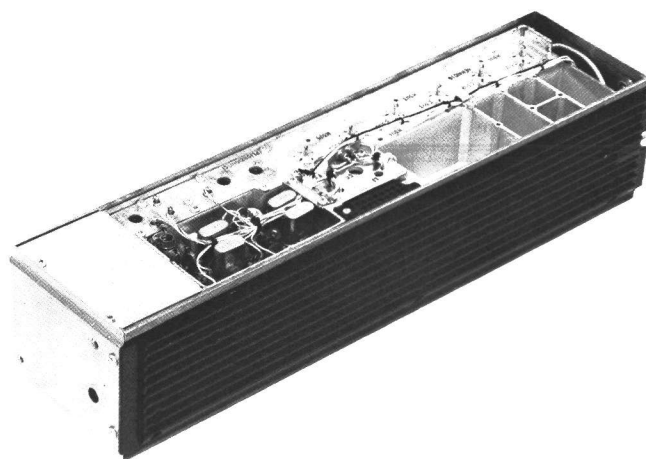




MASTR[®] PROGRESS LINE

132-174 MHz RECEIVER MODELS 4ER41D10-15 (WIDE BAND)



SPECIFICATIONS *

FCC Filing Designation

ER-41-D

Frequency Range

132—174 MHz

Audio Output

5 watts at less than 5% distortion

Sensitivity

12-dB SINAD (EIA Method) 0.40 μ V
20-dB Quieting Method 0.55 μ V

Selectivity

EIA Two-Signal Method -85 dB (adjacent channel, ± 60 kHz channels)
20-dB Quieting Method -100 dB at ± 35 kHz

Spurious Response

-100 dB

First Oscillator Stability

$\pm .0005\%$ (-30°C to $+60^{\circ}\text{C}$)

Modulation Acceptance

± 17 kHz (wide-band)

Squelch Sensitivity

Critical Squelch 0.2 μ V
Maximum Squelch Greater than 20 dB quieting (less than 2 μ V)

Intermodulation (EIA)

-70 dB

Maximum Frequency Separation

0.4%

Frequency Response

+1 and -8 dB of a standard 6-dB per octave
de-emphasis curve from 300 to 3000 Hz
(1000-Hz reference)

*These specifications are intended primarily for the use of the serviceman. Refer to the appropriate Specification Sheet for the complete specifications.

TABLE OF CONTENTS

SPECIFICATIONS	Cover
DESCRIPTION	1
CIRCUIT ANALYSIS	1
Helical Resonators	1
Oscillator/Multiplier Board	2
2nd Multiplier	2
1st Mixer	2
High IF Amplifier and Crystal Filter	2
2nd Oscillator, 2nd Mixer and 1st IF Amplifier	2
2nd Lo IF Amplifier and Limiters	2
Discriminator	3
Audio-Noise Amplifier	3
Audio Amplifiers	3
Squelch	3
MAINTENANCE	4
Disassembly	4
Alignment Procedure	5
Test Procedures	6
Audio Power Output and Distortion	6
Usable Sensitivity (12-dB SINAD)	6
Modulation Acceptance Bandwidth	6
Receiver Troubleshooting	7
OUTLINE DIAGRAM	8
SCHEMATIC DIAGRAM	10
PARTS LIST	9
PRODUCTION CHANGES	12

ILLUSTRATIONS

Figure 1 Block Diagram	1
Figure 2 FET Nomenclature	2
Figure 3 Removing Top Cover	4
Figure 4 Removing Bottom Cover	4
Figure 5 Test Setup for 20-Hz Double-Trace Sweep Alignment	5
Figure 6 Detector Probe for Sweep Alignment	5

WARNING

No one should be permitted to handle any portion of the equipment that is supplied with high voltage; or to connect any external apparatus to the units while the units are supplied with power. KEEP AWAY FROM LIVE CIRCUITS.

DESCRIPTION

General Electric MASTR Progress Line Receiver Type ER-41-D is a double conversion, superheterodyne wide-band FM receiver designed for operation on the 132-174 megahertz band.

The receiver is of single-unit construction and is completely housed in an aluminum casting for maximum shielding and rigidity. The top compartment of the casting contains the RF, oscillator, mixer, high IF and 1st low IF amplifier stages. The bottom portion of the casting contains the audio squelch board, crystal filter and audio PA stage.

Input leads to the receiver are individually filtered by the 20-pin feed-through by-pass connector J443. A regulated +10 volts is used for all receiver stages except the audio PA stage which operates from the 12-volt system supply.

Centralized metering jack J442 is provided for use with General Electric Test Set Model 4EX3A10 or 4EX8K11 for ease of alignment and servicing. The Test Set meters the oscillator, multiplier, and limiter stages as well as the discriminator and regulated 10 volts.

A block diagram of the receiver is shown in Figure 1.

CIRCUIT ANALYSIS

The MASTR Progress Line Receiver is completely transistorized, using silicon transistors throughout for added reliability.

HELICAL RESONATORS

Five tuned helical resonators (L301/L302 through L309/L310) provide the RF selectivity in the front end. RF cable W441 connects the RF signal from the antenna to a tap on L301/L302. The tap on L301/L302

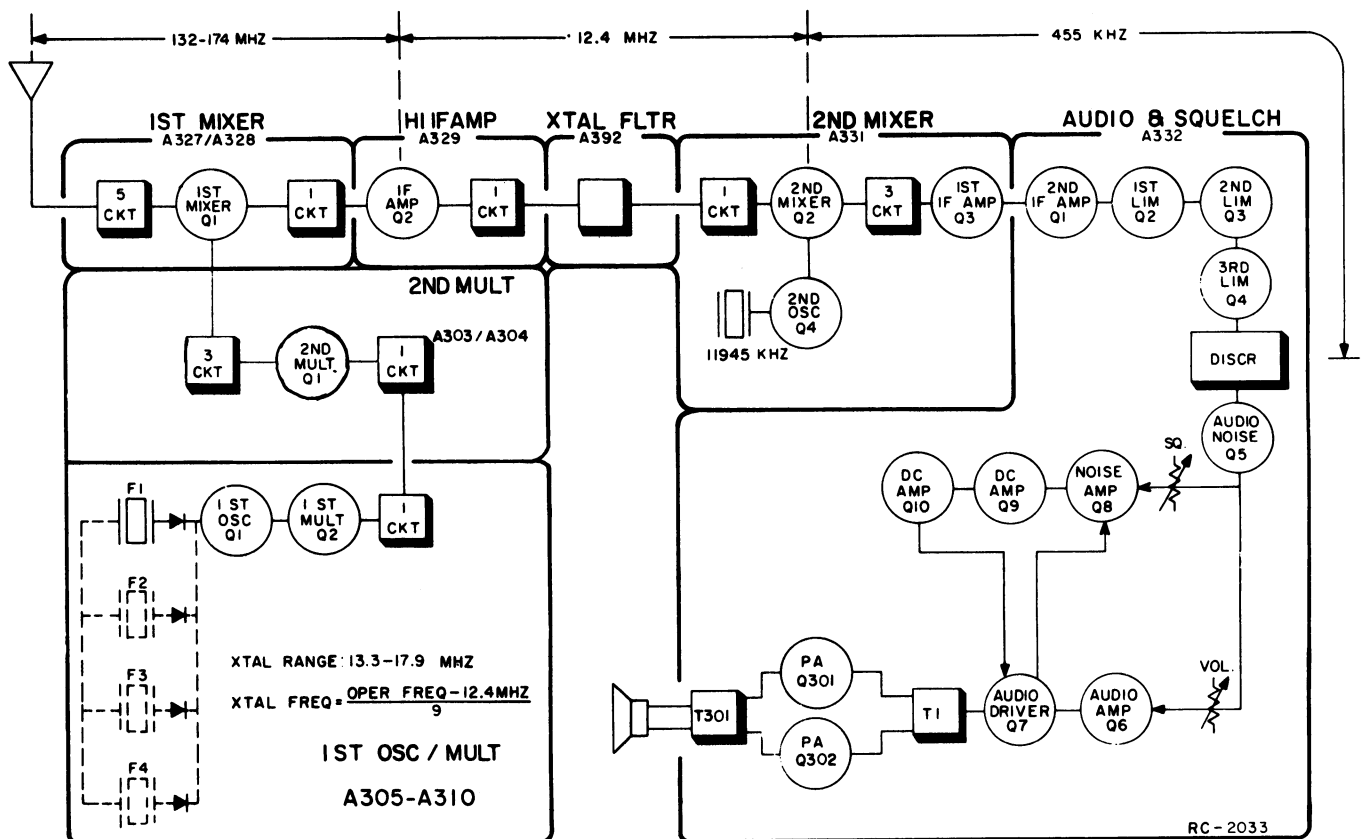


Figure 1 - Receiver Block Diagram

is positioned to provide the proper impedance match to the first mixer. The output of the helical resonators is coupled through C3 to the 1st Mixer Assembly.

OSCILLATOR/MULTIPLIER (A305-A310)

The receiver 1st oscillator operates in a transistorized Colpitts oscillator circuit. The oscillator crystal operates in a fundamental mode at a frequency of approximately 13 to 18 megahertz. The crystal is cut to provide temperature compensation at the high end of the temperature range and is thermistor compensated at low temperature. This provides $\pm 0.0005\%$ frequency stability as soon as the receiver is energized -- without the warm-up time required by crystal ovens or warmers.

In single frequency receivers, bias for the oscillator transistor is obtained by a jumper from H1 to H2 on the oscillator board.

In multi-frequency receivers, a diode is connected in series with the crystal, and up to three addition crystal circuits can be added. The 10-volt jumper is removed, and the proper frequency is selected by switching the desired crystal circuit to +10 volts by means of a frequency selector switch on the control unit.

Switching the +10 volts to the crystal circuit forward biases the diode and reduces its impedance. This applies the crystal frequency to the base of oscillator transistor Q1. Feedback for the oscillator is developed across C21. The output is coupled to the base of 1st multiplier Q2.

The output of the 1st multiplier (trippler Q2) is transformer-coupled (T1/T2) to the 2nd multiplier assembly. The 1st multiplier tank is tuned to three times the crystal frequency, and is metered at centralized metering jack J442-4 through metering network CR5, R16, R5 and C33.

2ND MULTIPLIER (A303/A304)

The 1st multiplier output is transformer-coupled through A303-T1/T2 to the base of 2nd multiplier A303-Q1. Following the 2nd multiplier are two resonant L-C circuits and a helical resonator tuned to nine times the crystal frequency. The output is taken from a tap on L311/L312 and applied to the 1st mixer.

1ST MIXER (A327/A328)

The 1st mixer uses a Field-Effect Transistor (FET) as the active device. The FET may be considered a semiconductor current path (or channel) whose resistance is varied by a voltage applied to the control element (gate). Lead identification for the

FET is shown in Figure 2A.

The FET has several advantages over a conventional transistor, including a high input impedance, high power gain, and an output that is relatively free of harmonics (low in intermodulation products). The FET also has voltage-controlled characteristics, and may be compared to a vacuum tube in operation (see Figure 2B).

RF from the helical resonators is applied to the gate of Q1, and injection voltage from the multiplier is applied to the source. The mixer output is taken from the drain with the output tuned to the 12.4 MHz high IF frequency.

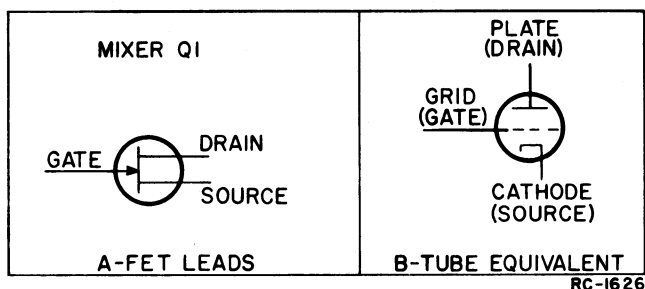


Figure 2 - FET Nomenclature

HI IF AMPLIFIER (A329) AND CRYSTAL FILTER (A330)

The mixer output is coupled through A327-C6 to the emitter of the high IF amplifier A329. The transistor is connected as a grounded-base amplifier which provides a low impedance for the mixer input. The amplifier output is coupled through transformer T1 to the crystal filter.

The highly-selective crystal filter (A330) provides the major selectivity for the receiver. The output of the filter is coupled through impedance-matching transformer A331-T2 to the base of the 2nd mixer.

2ND OSCILLATOR, 2ND MIXER AND 1ST LO IF AMPLIFIER (A331)

A331-Q4 operates in a Colpitts oscillator circuit, with feedback supplied through C18. The oscillator low-side injection voltage (11,945 kHz) is applied to the base of the 2nd mixer.

The High IF signal from the filter and the injection voltage from the 2nd oscillator is applied to the base of 2nd mixer Q2. The 445-kHz mixer output is applied to three tuned low IF circuits, L1, L2 and L3. These tuned circuits are required for shaping the nose of the IF waveform, and for rejecting any undesired output frequencies from the 2nd mixer.

The low IF signal is applied to the

base of 1st low IF amplifier Q3. The output of Q3 is R-C coupled to the base of the 2nd low IF amplifier.

2ND LO IF AMPLIFIER AND LIMITERS (A332)

Additional amplification of the low IF signal going to the limiter stages is provided by 2nd low IF amplifier A332-Q1. This stage is metered at J442-2 through a metering network consisting of C19, CR3 and R25.

Following the 2nd low IF amplifier are three R-C coupled limiter stages (Q2, Q3 and Q4). The 1st limiter is metered at J442-3 through metering network C20, CR4 and R26.

DISCRIMINATOR (A332)

The limiter output is applied to a Foster-Seely type discriminator, where diodes CR1 and CR2 rectify the 455-kHz signal to recover the audio. The discriminator is metered at J442-10 through metering network C56 and R23.

AUDIO - NOISE AMPLIFIER (A322)

The discriminator output is coupled through a low-pass filter (C56, C18, R69 and R83) to the base of audio-noise amplifier Q5. The filter removes any 455-kHz signal remaining in the discriminator output. Q5 operates as an emitter-follower to match the discriminator impedance to the VOLUME and SQUELCH CONTROL. The stage also provides power gain.

AUDIO AMPLIFIERS (A332)

Any audio present in the incoming signal is coupled from the emitter of Q5 through the VOLUME control, and applied to the base of audio amp Q6 through a de-emphasis network. The de-emphasis network consists of C22, C23, R30 and R31.

Audio driver Q7 follows the audio amplifier. The output of Q7 is coupled through transformer T1 to provide phase inversion for the push-pull audio PA stage.

Q301 and Q302 operate as a push-pull, Class AB audio PA stage. The PA output is coupled through audio transformer T301 to the loudspeaker. The yellow and white tertiary windings of T301 supply balanced feedback to the collector of Q7 to minimize distortion.

Base bias for the PA stage and the elimination of crossover distortion is controlled by bias adjust potentiometer R43. The potentiometer is set at the factory as shown in STEP 1 of the receiver Test Procedure.

NOTE

Do not adjust bias adjust potentiometer R43 unless PA transistors Q301 and Q302 have been replaced.

Audio high and low are also present at centralized metering jack J442, and can be used as shown in STEP 1 of the Receiver Test Procedure. The output stage provides 5 watts at less than 5% distortion into a 3.5-ohm load at the receiver output terminals (3.2-ohm load at the Control Unit).

SQUELCH (A332)

Noise from the audio-noise amplifier (Q5) operates the squelch circuit. With no carrier present in the receiver, this noise is coupled to the base of noise amplifier Q8 through a high-pass filter which attenuates frequencies below 3 kHz. The filter consists of C58, C59 and R45, as well as C57 and L3 in the collector circuit of Q8. The gain of Q8 is determined by the SQUELCH control, which varies the bias on the base of Q8. Thermistor RT2 keeps the critical squelch constant over wide variations in temperature.

The output of noise amplifier Q8 is rectified by diodes CR5 and CR6, and filtered by C36 and C37 to produce a negative DC voltage. This DC voltage is applied to the base of DC amplifier Q9, turning it off. When turned off, the collector voltage of Q9 rises to approximately 8 volts, turning on DC amplifier Q10. When conducting, the collector voltage of Q10 drops to almost ground potential, which removes the base bias to audio amplifier Q6 and audio driver Q7, turning them off.

When the receiver is quieted by a signal (unsquelches), the noise in the receiver is reduced, turning DC amplifier Q9 on and DC amplifier Q10 off. This allows the audio stages to conduct so that sound is heard in the speaker.

Resistor R73 connects from the emitter of audio driver Q7 to the emitter of noise amplifier Q8, providing a hysteresis loop in the squelch circuit. When a weak signal opens the squelch, the signal level may be reduced by 4 to 6 dB without the squelch closing. This limits squelch "flutter" or "picket-fence" operation.

With audio driver Q7 conducting, a positive voltage through R73 helps to reduce the gain of noise amplifier Q8. This positive feedback provides a quick, positive switching action in the squelch circuit. When the receiver squelches, audio driver Q7 turns off and its emitter potential drops to zero. This reduces the DC feedback causes Q8 to conduct harder, turning the audio stages off quickly.

Keying the transmitter removes the +10 volts from J19, turning off DC amplifier Q9 and turning on Q10 to mute the receiver.

MAINTENANCE

To service the receiver from the top—

1. Pull locking handle down and pull radio about one inch out of mounting frame.
2. Pry up cover at rear of receiver.
3. Slide cover back and lift off.

To service the receiver from the bottom—

1. Pull locking handle down. Pull radio out of mounting frame.

2. Remove screws in bottom cover. Pry up cover at back of receiver.
3. Slide cover back and lift off.

To remove the receiver from the system frame—

1. Loosen the two Phillips-head retaining screws in front casting (see Figure 3), and pull casting away from system frame.
2. Remove the four screws in the back cover.
3. Remove the two screws holding the receiver at each end of the system frame.
4. Disconnect the antenna jack and the 20-pin connector from the front of the receiver, and slide the unit out of the system frame.

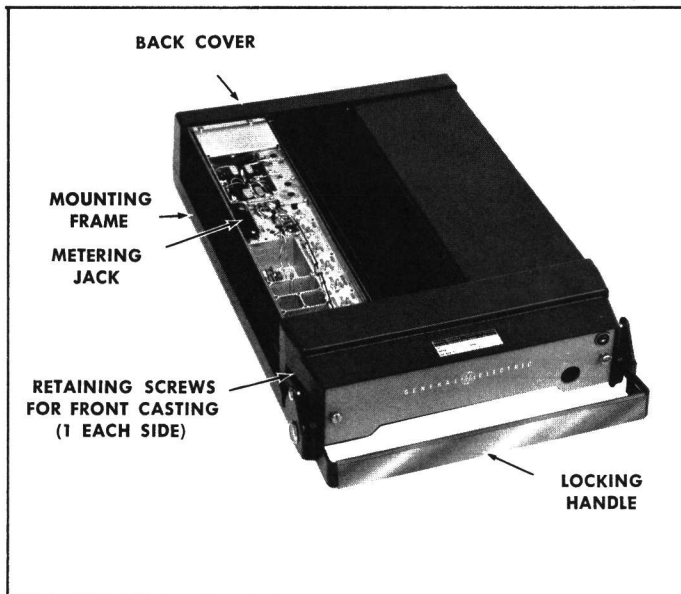


Figure 3 - Removing Top Cover

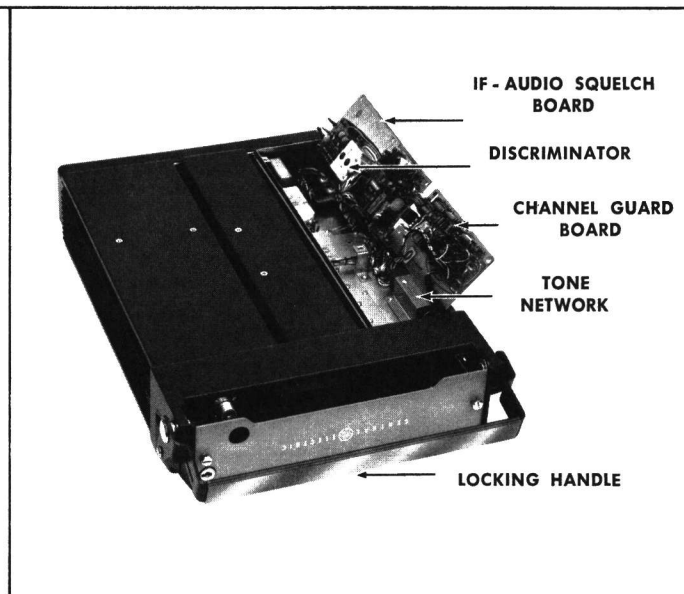


Figure 4 - Removing Bottom Cover

TEST PROCEDURES

These Test Procedures are designed to help you to service a receiver that is operating---but not properly. The problems encountered could be low power, poor sensitivity, distortion, limiter not operating properly, and low gain. By following the sequence of test steps starting with Step 1, the defect can be quickly localized. Once

the defective stage is pin-pointed, refer to the "Service Check" listed to correct the problem. Additional corrective measures are included in the Troubleshooting Procedure. Before starting with the Receiver Test Procedures, be sure the receiver is tuned and aligned to the proper operating frequency.

TEST EQUIPMENT REQUIRED

- Distortion Analyzer similar to: Heath IM-12
- Signal Generator similar to: Measurements M-560
- 6-dB attenuation pad, and 3.5-ohm, 10-watt resistor

PRELIMINARY ADJUSTMENTS

1. Connect the test equipment to the receiver as shown for all steps of the receiver Test Procedure.
2. Turn the SQUELCH control fully clockwise for all steps of the Test Procedure.
3. Turn on all of the equipment and let it warm up for 20 minutes.

STEP 1 AUDIO POWER OUTPUT AND DISTORTION

TEST PROCEDURE

Measure Audio Power Output as follows:

- A. Apply a 1,000-microvolt, on-frequency test signal modulated by 1,000 hertz with ± 10 kHz deviation to antenna jack J441.

- B. With Five-Watt Speaker:

Disconnect speaker lead pin from J701-2 (on rear of Control Unit).

Connect a 3.5-ohm load resistor from J442-15 to J442-7. Connect the Distortion Analyzer input across the resistor as shown.

OR

With Handset:

Lift the handset off of the hookswitch. Connect the Distortion Analyzer input from J442-15 to J442-7.

- C. Adjust the VOLUME control for five-watt output (4.18 VRMS using the Distortion Analyzer as a VTVM).
- D. Make distortion measurements according to manufacturer's instructions. Reading should be less than 5%. If the receiver sensitivity is to be measured, leave all controls and equipment as they are.

SERVICE CHECK

If the distortion is more than 5%, or maximum audio output is less than five watts, make the following checks:

- E. Battery and regulator voltage---low voltage will cause distortion. (Refer to Receiver Schematic Diagram for voltages.)
- F. P.A. Bias Adjust (R43) -- Turn the SQUELCH control fully counterclockwise.

Then connect a milliammeter in series with the +12 volt lead at P443-11. With no signal in, adjust R43 for a reading of approximately 20 milliamps. This adjustment should not be necessary unless an output transistor has been replaced.

- G. Audio Gain (Refer to Receiver Troubleshooting Procedure).
- H. Discriminator Alignment (Refer to Receiver Alignment on reverse side of page).

STEP 2 USABLE SENSITIVITY (12-dB SINAD)

If STEP 1 checks out properly, measure the receiver sensitivity as follows:

- A. Apply a 1000-microvolt, on-frequency signal modulated by 1000 Hz with 10-kHz deviation to J441.
- B. Place the RANGE switch on the Distortion Analyzer in the 200 to 2000-Hz distortion range position (1000-Hz filter in the circuit). Tune the filter for minimum reading or null on the lowest possible scale (100%, 30%, etc.)
- C. Place the RANGE switch to the SET LEVEL position (filter out of the circuit) and adjust the input LEVEL control for a +2 dB reading on a mid range (30%).
- D. While reducing the signal generator output, switch the RANGE control from SET LEVEL to the distortion range until a 12-dB difference (+2 dB to -10 dB) is obtained between the SET LEVEL and distortion range positions (filter out and filter in).
- E. The 12-dB difference (Signal plus Noise and Distortion to noise plus distortion ratio) is the "usable" sensitivity level. The sensitivity should be less than rated 12 dB SINAD specification with an audio output of at least 2.5 watts (2.9 volts RMS across the 3.5-ohm receiver load using the Distortion Analyzer as a VTVM).

- F. Leave all controls as they are and all equipment connected if the Modulation Acceptance Bandwidth test is to be performed.

SERVICE CHECK

If the sensitivity level is more than rated 12 dB SINAD, check the alignment of the RF stages as directed in the Alignment Procedure, and make the gain measurements as shown on the Troubleshooting Procedure.

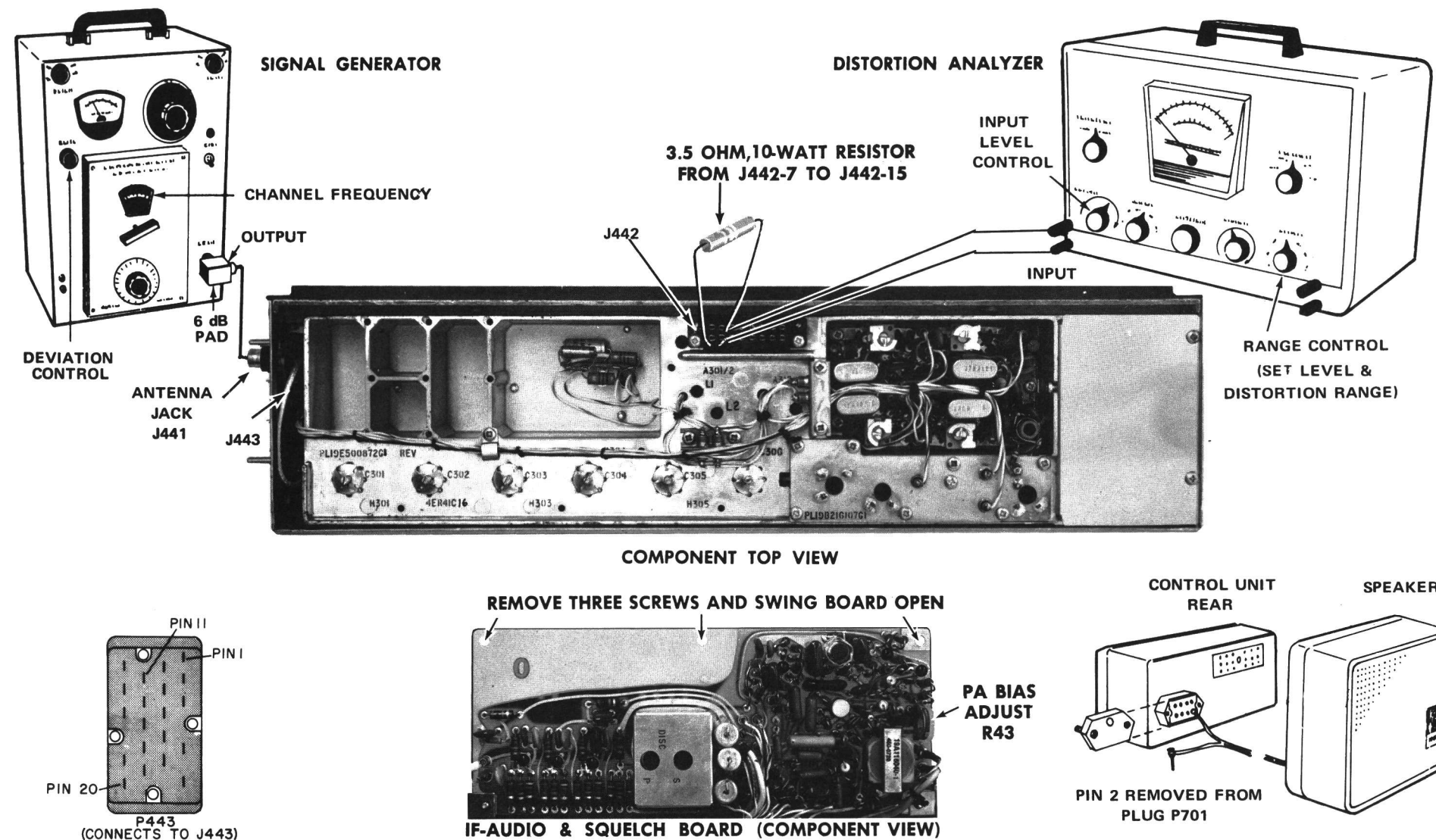
STEP 3 MODULATION ACCEPTANCE BANDWIDTH (IF BANDWIDTH)

If STEPS 1 and 2 check out properly, measure the bandwidth as follows:

- A. Set the Signal Generator output for twice the microvolt reading obtained in the 12-dB SINAD measurement.
- B. Set the RANGE control on the Distortion Analyzer in the SET LEVEL position (1000-Hz filter out of the circuit), and adjust the input LEVEL control for a +2 dB reading on the 30% range.
- C. While increasing the deviation of the Signal Generator, switch the RANGE control from SET LEVEL to distortion range until a 12-dB difference is obtained between the SET LEVEL and distortion range readings (from +2 dB to -10 dB).
- D. The deviation control reading for the 12-dB difference is the Modulation Acceptance Bandwidth of the receiver. It should be more than ± 15 kHz (but less than ± 19 kHz).

SERVICE CHECK

If the Modulation Acceptance Bandwidth test does not indicate the proper width, make gain measurements as shown on the Receiver Troubleshooting Procedure.



STEP 1-QUICKCHECKS

TEST SET CHECKS

These checks are typical voltage readings measured with GE Test Set Model 4EX3A10 in the Test 1 position, or Model 4EX8K10 or 11 in the 1-volt position.

Metering Position	Reading with No Signal in	Reading with 1 μv unmodulated input
A Disc idling	Less than ±.05 VDC	
B 2nd IF	0.2 VDC	0.2 VDC
C 1st Lim	0.7 VDC	0.8 VDC
D Mult 1	0.6 VDC	
E Mult 2	.8 VDC	
J Regulated +10 Volts	10 VDC	

SYMPTON CHECKS

SYMPTOM	PROCEDURE
NO SUPPLY VOLTAGE	• Check power connections and continuity of supply leads, and check fuse in power supply. If fuse is blown, check receiver for short circuits.
NO REGULATED 10-VOLTS	• Check the 12-volt supply. Then check regulator circuit (See Troubleshooting Procedure for Power Supply).
LOW 1ST LIM READING	• Check supply voltages and then check oscillator reading at J442-4 & 5 as shown in STEP 2A. • Make SIMPLIFIED VTVM GAIN CHECKS from 2nd Mixer through 1st Limiter stages as shown in STEP 2A.
LOW OSCILLATOR/MULTIPLIER READINGS	• Check alignment of Oscillator (Refer to Front End Alignment Procedure). • Check voltage and resistance readings of 1st Oscillator/Multiplier Q1/Q2. • Check crystal Y1.
LOW RECEIVER SENSITIVITY	• Check Front End Alignment (Refer to Receiver Alignment Procedure). • Check antenna connections, cable and relay. • Check 1st and 2nd Oscillator injection voltage. • Check voltage and resistance readings of 1st Mixer, HI IF Amp and 2nd Mixer. • Make SIMPLIFIED GAIN CHECKS (STEP 2A).
LOW AUDIO	• Check Audio PA (Q301 & Q302) voltage readings on schematic diagram. • Make simplified gain and waveform checks of audio and squelch stages (Steps 2A and 2B). • Make unsquelched voltage readings in Audio section (Refer to Receiver Schematic Diagram). • Check voltage and resistance readings on Channel Guard board.
HIGH DISTORTION AT LOW AUDIO LEVELS (50 MW)	• Set PA bias adjust R43 as specified under Service. • Checks in STEP 1 of TEST PROCEDURES.
IMPROPER SQUELCH OPERATION	• Check voltage and resistance readings of Squelch circuit (Refer to Receiver Schematic Diagram). • Make gain and waveform checks of audio and squelch stages (Steps 2A and 2B).
DISCRIMINATOR IDLING TOO FAR OFF ZERO	• See if discriminator zero is in center of IF bandpass.

STEP 3-VOLTAGE RATIO READINGS

EQUIPMENT REQUIRED:

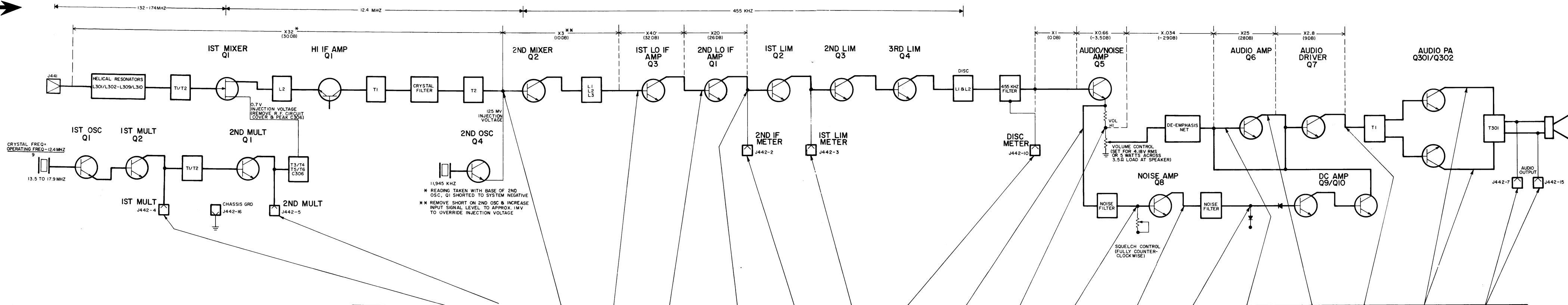
- RF Voltmeter (Similiar to Boonton Model 91-CA or Millivac Type MV-18 C).
- Signal on receiver frequency (below saturation). Correct frequency can be determined by zeroing the discriminator. Use 1,000 Hertz signal with 3.0 kHz deviation for audio stage.

PROCEDURE

- Apply probes to input of stage and system negative (-10 VDC). Take voltage reading (E₁).
- Move probes to input of following stage and system negative. Take reading (E₂).
- Convert readings by means of the following formula:

$$\text{Voltage Ratio} = \frac{E_2}{E_1}$$

- Check results with typical voltage ratios shown on diagram.



STEP 2A-SIMPLIFIED VTVM GAIN CHECKS

EQUIPMENT REQUIRED:

- VTVM-AC & DC
- Signal Generator (measurements M560 or equiv.)

PRELIMINARY STEPS:

- Set VOLUME control for 4.18 volts across 3.5-ohm load. If this cannot be obtained, set to approx. 70% of max. rotation.
- Set SQUELCH control fully counterclockwise.
- Receiver should be properly aligned.
- Connect VTVM between system negative and points indicated by arrow (except for 1st and 2nd MULT which reference chassis ground).

SIGNAL GENERATOR INPUT AT J441 MAINTAIN SETTING AT DISCRIMINATOR ZERO			UNMODULATED	UNMODULATED	UNMODULATED	UNMODULATED	UNMODULATED	1 MICROVOLT UNMODULATED	NO SIGNAL INPUT	STANDARD SIGNAL-1 (1 MILLIVOLT AT RCVR FREQ MODULATED BY 1KHZ WITH 10 KHZ DEVIATION)	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL	STANDARD SIGNAL
PROCEDURE			INCREASE GENERATOR OUTPUT UNTIL VTVM READING ON 15 V SCALE DECREASES BY 50 MV	INCREASE SIGNAL GENERATOR OUTPUT FROM ZERO UNTIL VTVM READING DECREASES BY 5 %	INCREASE SIGNAL GENERATOR OUTPUT FROM ZERO UNTIL VTVM READING DECREASES BY 5 %	INCREASE SIGNAL GENERATOR OUTPUT FROM ZERO UNTIL VTVM READING DECREASES BY 5 %	INCREASE SIGNAL GENERATOR OUTPUT FROM ZERO UNTIL VTVM READING DECREASES BY 5 %															CONNECT VTVM OR SCOPE ACROSS 3.5Ω LOAD BETWEEN J442-7 AND J442-5 WITH SPEAKER DISCONNECTED.
READING	5 VDC GE TEST SET (POS. D. 0.6V)	2.5 VDC GE TEST SET (POS. E. 8V)	GENERATOR OUTPUT SHOULD BE APPROX 20 MILLIVOLTS	GENERATOR OUTPUT SHOULD BE APPROX 600 MICROVOLTS	GENERATOR OUTPUT SHOULD BE APPROX 5 MICROVOLTS	GENERATOR OUTPUT SHOULD BE APPROX 0.3 MICROVOLTS	GENERATOR OUTPUT SHOULD BE APPROX 0.3 MICROVOLTS	0.6 VDC GE TEST SET (POS. B. 0.2V)	2 VDC GE TEST SET (POS. C. 0.7V)	0.8 VAC	0.75 VAC	0.55 VAC	0.15 VAC	2.3 VAC	0.05 VAC		0.5 VAC	1.4 VAC	10 VAC	4.18 VAC		

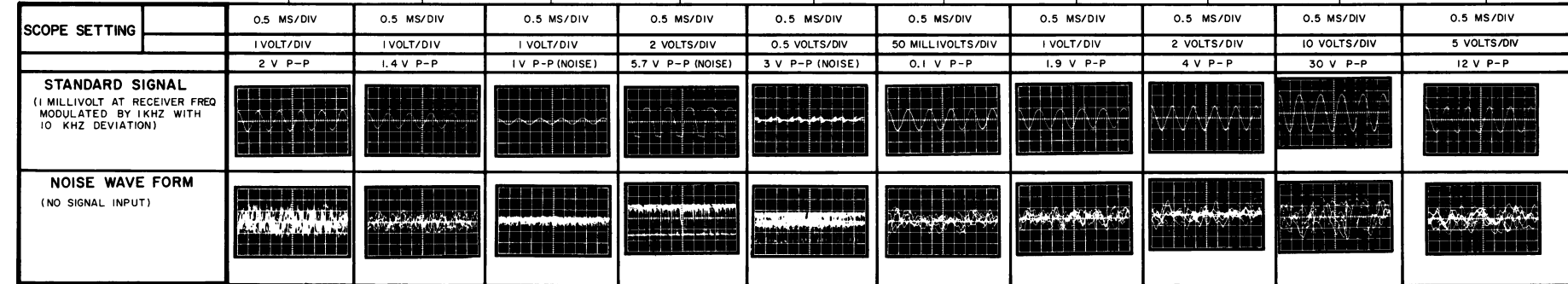
STEP 2B-AUDIO & SQUELCH WAVEFORMS

EQUIPMENT REQUIRED:

- Oscilloscope.
- Signal generator (measurements M560 to equivalent).

PRELIMINARY STEPS:

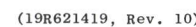
- Set VOLUME control for 4.18 volts across 3.5-ohm load. If this cannot be obtained, set to approx. 70% of max. rotation.
- Set SQUELCH control fully counterclockwise.
- Receiver should be properly aligned.
- Connect oscilloscope between system negative and points indicated by arrow.



TROUBLE SHOOTING PROCEDURE

132—174 MHz MASTR RECEIVER
MODELS 4ER41D10-15

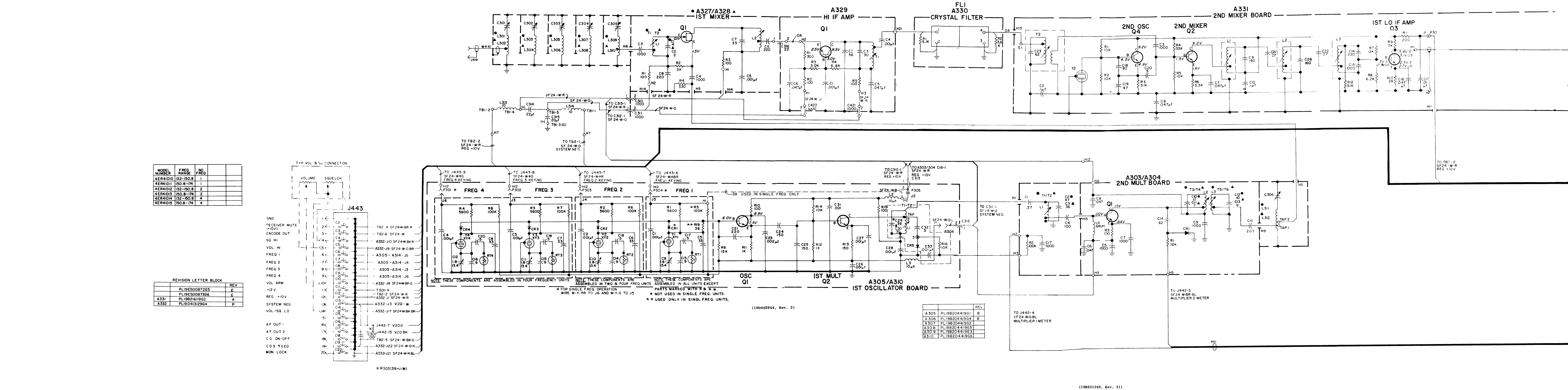
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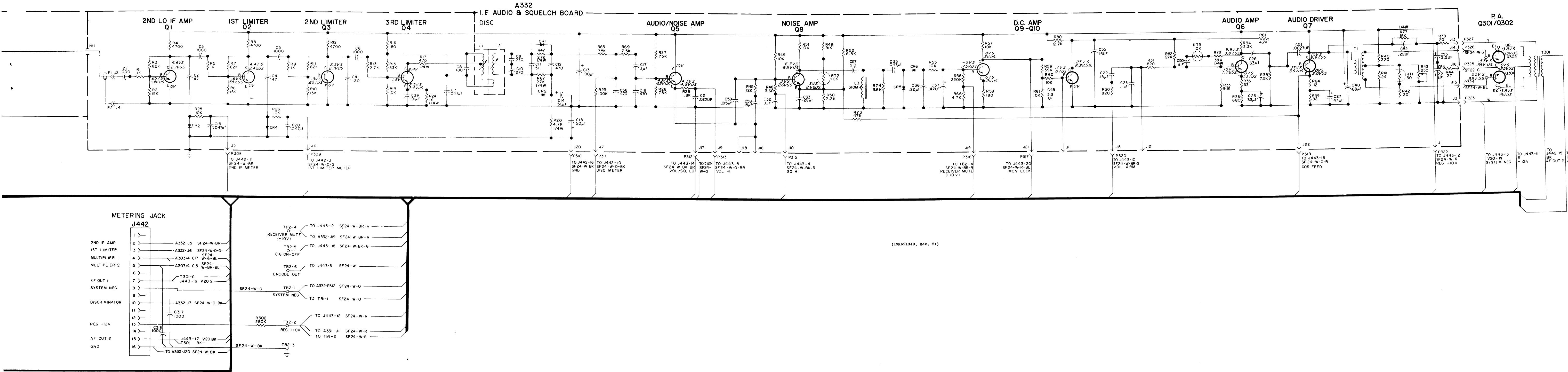


PARTS LIST		
LB141998 132-174 MHz RECEIVER MODELS 4BR4D10-15		
SYMBOL	GE PART NO.	DESCRIPTION
A303* and A304*		SECOND MULTIPLIER A303 19B21908G1 LOW SPLIT A304 19B21908G2 HIGH SPLIT (Added by REV C)
C1	5491601P107	Phenolic: 0.27 pf ±5%, 500 VDCW.
C4	5496203P133	Ceramic disc: 100 pf ±10%, 500 VDCW, temp coef -3300 PPM.
C5	5494481P11	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.
C6	19A116080P105	Polyester: 0.047 µf ±10%, 50 VDCW.
C7	5494481P11	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.
C8	19A116080P105	Polyester: 0.047 µf ±10%, 50 VDCW.
C9	5494481P11	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.
C14	5491601P16	Phenolic: 0.62 pf ±10%, 500 VDCW; sim to Quality Components Type MC.
C15	5494481P11	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.
C17	5494481P11	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.
CR1	19A115250P1	Silicon, fast recovery, 225 mA, 50 PIV.
L4	19B209420P111	Coil, RF: 0.68 µh ±10%, 0.54 ohms DC res max; sim to Jeffers 4426-4K.
Q1	19A115440P1	Silicon, NPN.
R1	3R152P103K	Composition: 10K ohms ±10%, 1/4 w.
R2	3R152P104K	Composition: 100K ohms ±10%, 1/4 w.
R3	3R152P101K	Composition: 100 ohms ±10%, 1/4 w.
T1 and T2		COIL ASSEMBLY T1 19B216097G3 T2 19B216097G4
C2	5496218P255	Ceramic disc: 47 pf ±5%, 500 VDCW, temp coef -80 PPM.
C3	5496218P252	Ceramic disc: 36 pf ±5%, 500 VDCW, temp coef -80 PPM.
	19B216097P6 5491798P5	Coil. Tuning slug.
T3 and T4		COIL ASSEMBLY T3 19B216106G3 T4 19B216106G4
C10	5496218P241	Ceramic disc: 10 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.
C11	5496218P238	Ceramic disc: 7.0 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.

SYMBOL	GE PART NO.	DESCRIPTION
T3 and T4		COIL ASSEMBLY T3 19B216106G3 T4 19B216106G2
C9	5494481P11	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.
C10	5496218P241	Ceramic disc: 10 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.
C11	5496218P238	Ceramic disc: 7.0 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.
CR1	19A115250P1	Silicon.
L2	19B216106P6 5491798P5	Coil. Tuning slug.
T5 and T6		COIL ASSEMBLY T5 19B216102G1 T6 19B216102G2
C12	5496218P241	Ceramic disc: 10 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.
C13	5496218P239	Ceramic disc: 8.0 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.
C16	5496218P770	Ceramic disc: 200 pf ±5%, 500 VDCW, temp coef -750 PPM.
L3	19B216102P6 5491798P5	Coil. Tuning slug.
A303* and A304*		SECOND MULTIPLIER A303 19B216107G1 A304 19B216107G2
C5	5493392P7	Ceramic, feed-thru: 1000 pf ±100% -0%, 500 VDCW; sim to Allen Bradley Type FAS3.
C6	19A116080P105	Polyester: 0.047 µf ±10%, 50 VDCW.
C7	5494481P11	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.
C8	19A116080P105	Polyester: 0.047 µf ±10%, 50 VDCW.
C14	5491601P16	Phenolic: 0.62 pf ±10%, 500 VDCW; sim to Quality Components Type MC.
C15	5493392P7	Ceramic, feed-thru: 1000 pf ±100% -0%, 500 VDCW; sim to Allen Bradley Type FAS3.
C17 and C18	5493392P7	Ceramic, feed-thru: 1000 pf ±100% -0%, 500 VDCW; sim to Allen Bradley Type FAS3.
L4	19B209420P111	Coil, RF: 0.68 µh ±10%, 0.54 ohms DC res max; sim to Jeffers 4426-4K.
Q1	19A115440P1	Silicon, NPN.
R1	3R152P103K	Composition: 10K ohms ±10%, 1/4 w.
R2	3R152P104K	Composition: 100K ohms ±10%, 1/4 w.
R3	3R152P101K	Composition: 100 ohms ±10%, 1/4 w.
T1 and T2		COIL ASSEMBLY T1 19B216097G3 T2 19B216097G4
C2	5496218P255	Ceramic disc: 47 pf ±5%, 500 VDCW, temp coef -80 PPM.
C3	5496218P252	Ceramic disc: 36 pf ±5%, 500 VDCW, temp coef -80 PPM.
	19B216097P6 5491798P5	Coil. Tuning slug.
T3 and T4		COIL ASSEMBLY T3 19B216106G3 T4 19B216106G4
C10	5496218P241	Ceramic disc: 10 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.
C11	5496218P238	Ceramic disc: 7.0 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.

SYMBOL	GE PART NO.	DESCRIPTION
T3 and T4		COIL ASSEMBLY T3 19B216106G3 T4 19B216106G2
C9	5494481P11	Ceramic disc: 1000 pf ±20%, 1000 VDCW; sim to RMC Type JF Discap.
C10	5496218P241	Ceramic disc: 10 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.
C11	5496218P238	Ceramic disc: 7.0 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.
CR1	19A115250P1	Silicon.
L2	19B216106P6 5491798P5	Coil. Tuning slug.
T5 and T6		COIL ASSEMBLY T5 19B216102G1 T6 19B216102G2
C12	5496218P241	Ceramic disc: 10 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.
C13	5496218P239	Ceramic disc: 8.0 pf ±0.25 pf, 500 VDCW, temp coef -80 PPM.
C16	5496218P770	Ceramic disc: 200 pf ±5%, 500 VDCW, temp coef -750 PPM.
L3	19B216102P6 5491798P5	Coil. Tuning slug.
TBI	7487424P7	Miniature, phen: 4 terminals.
A305 thru A310		FIRST OSCILLATOR A305 19B204419G1 REV B A306 19B204419G4 REV B A307 19B204419G2 A30





IN ORDER TO RETAIN RATED EQUIPMENT PERFORMANCE, REPLACEMENT OF ANY SERVICE PART SHOULD BE MADE ONLY WITH A COMPONENT HAVING THE SPECIFICATIONS SHOWN ON THE PARTS LIST FOR THAT PART.

ALL RESISTORS ARE 1/2 WATT UNLESS OTHERWISE SPECIFIED AND RESISTOR VALUES IN OHMS UNLESS FOLLOWED BY K=1000 OHMS OR MEG=1,000,000 OHMS. CAPACITOR VALUES IN MICROFARADS (EQUAL TO MICROMICROFARADS) UNLESS FOLLOWED BY UF= MICROFARADS. INDUCTANCE VALUES IN MICROHENRYS UNLESS FOLLOWED BY MH= MILLIHENRYS OR H=HENRYS.

VOLTAGE READINGS
VOLTAGE READINGS ARE TYPICAL READINGS MEASURED TO SYSTEM NEGATIVE (J442-B) WITH TEST SET MODEL 4EX3A10 OF A 20,000 OHM PER-VOLT METER.

S = NO SIGNAL IN WITH SQUELCH CONTROL FULLY COUNTERCLOCKWISE (MAXIMUM SQUELCH).
US = SQUELCH CONTROL FULLY CLOCKWISE WITH A ONE MILLIVOLT MODULATED SIGNAL (UNSQUELCHED) AND 5 WATT AUDIO OUTPUT.

NOTE: DC VOLTAGES FOR 1ST MIXER, MULTIPLIER, AND 1ST IF AMPLIFIER TAKEN WITH MODULES REMOVED FROM CASTING AND 10 VOLTS APPLIED TO INPUT LEADS.

● LOW SPLIT 132-150.8 MHZ
▲ HIGH SPLIT 150.8-174 MHZ

(19K621349, Rev. 21)

SCHEMATIC DIAGRAM

132-174 MHz RECEIVER
MODELS 4ER41D10-15

SYMBOL	GE PART NO.	DESCRIPTION
		- - - - - INDUCTORS - - - - -
L1	19A115711P6	Transformer, freq: 455 KHz; sim to TOKO PEFCN-14733-CX12.
L2	19A115711P7	Transformer, freq: 455 KHz; sim to TOKO PEFCN-BNL2.
L3	19A127134G1	Choke. Includes tuning slug 7486872P7.
		- - - - - TRANSISTORS - - - - -
Q1 thru Q4	19A115123P1	Silicon, NPN.
Q5	19A115889P1	Silicon, NPN.
Q6	19A115123P1	Silicon, NPN.
Q7	19A115300P4	Silicon, NPN.
Q8	19A115123P1	Silicon, NPN.
Q9	19A115382P1	Silicon, NPN; sim to Type 2N2925.
Q10	19A116774P1	Silicon, NPN; sim to Type 2N5210.
		- - - - - RESISTORS - - - - -
R1	3R77P102K	Composition: 1K ohms $\pm 10\%$, 1/2 w.
R2	3R77P153J	Composition: 15K ohms $\pm 5\%$, 1/2 w.
R3	3R77P823K	Composition: 82K ohms $\pm 10\%$, 1/2 w.
R4	3R77P472K	Composition: 4.7K ohms $\pm 10\%$, 1/2 w.
R5	3R77P102K	Composition: 1K ohms $\pm 10\%$, 1/2 w.
R6	3R77P153J	Composition: 15K ohms $\pm 5\%$, 1/2 w.
R7	3R77P823K	Composition: 82K ohms $\pm 10\%$, 1/2 w.
R8	3R77P472K	Composition: 4.7K ohms $\pm 10\%$, 1/2 w.
R9	3R77P102K	Composition: 1K ohms $\pm 10\%$, 1/2 w.
R10	3R77P153J	Composition: 15K ohms $\pm 5\%$, 1/2 w.
R11	3R77P823K	Composition: 82K ohms $\pm 10\%$, 1/2 w.
R12	3R77P472K	Composition: 4.7K ohms $\pm 10\%$, 1/2 w.
R13	3R77P272K	Composition: 2.7K ohms $\pm 10\%$, 1/2 w.
R14	3R77P103J	Composition: 10K ohms $\pm 5\%$, 1/2 w.
R15	3R77P333J	Composition: 33K ohms $\pm 5\%$, 1/2 w.
R16	3R77P181K	Composition: 180 ohms $\pm 10\%$, 1/2 w.
R17	3R152P471J	Composition: 470 ohms $\pm 5\%$, 1/4 w.
R20	3R152P472K	Composition: 4.7K ohms $\pm 10\%$, 1/4 w.
R23	3R77P104K	Composition: 100K ohms $\pm 10\%$, 1/2 w.
R24	3R152P102J	Composition: 1K ohms $\pm 5\%$, 1/4 w.
R25 and R26	3R77P103K	Composition: 10K ohms $\pm 10\%$, 1/2 w.
R27 and R28	3R77P753J	Composition: 75K ohms $\pm 5\%$, 1/2 w.
R29	3R77P182J	Composition: 1.8K ohms $\pm 5\%$, 1/2 w.
R30 and R31	3R77P821J	Composition: 820 ohms $\pm 5\%$, 1/2 w.
R33	3R77P912J	Composition: 9.1K ohms $\pm 5\%$, 1/2 w.
R34	3R77P332K	Composition: 3.3K ohms $\pm 10\%$, 1/2 w.
R35	3R77P330K	Composition: 33 ohms $\pm 10\%$, 1/2 w.
R36	3R77P681J	Composition: 680 ohms $\pm 5\%$, 1/2 w.
R38	3R77P752J	Composition: 7.5K ohms $\pm 5\%$, 1/2 w.
R39	3R77P820J	Composition: 82 ohms $\pm 5\%$, 1/2 w.
R40*	3R77P221J	Composition: 220 ohms $\pm 5\%$, 1/2 w.
		In REV H and earlier:
	3R77P241J	Composition: 240 ohms $\pm 5\%$, 1/2 w.
R41	3R152P240J	Composition: 24 ohms $\pm 5\%$, 1/4 w.

SYMBOL	GE PART NO.	DESCRIPTION
C314	5496267P10	Tantalum: 22 μ f \pm 20%, 15 VDCW; sim to Sprague Type 150D.
C315	19A115680P3	Electrolytic: 20 μ f +150% -10%, 25 VDCW; sim to Mallory Type TTX.
C317 and C318	5494481P12	Ceramic disc: 1000 pf \pm 10%, 1000 VDCW; sim to RMC Type JF Discap.
----- DIODES AND RECTIFIERS -----		
CR1*	19A116082P2	Selenium. Deleted by REV A.
----- JACKS AND RECEPTACLES -----		
J441		(Part of W441).
J442	19B205689C2	Connector: 18 contacts.
J443	19C303426G1	Connector: 20 pin contacts.
----- INDUCTORS -----		
L301	19B216112G4	Coil.
L302	19B216112G3	Coil.
L303	19B216112P8	Coil.
L304	19B216112P7	Coil.
L305	19B216112P8	Coil.
L306	19B216112P7	Coil.
L307	19B216112P8	Coil.
L308	19B216112P7	Coil.
L309	19B216112G6	Coil.
L310	19B216112G5	Coil.
L311	19B216112G2	Coil.
L312	19B216112G1	Coil.
L313 and L314	7488079P16	Choke, RF: 10 μ h \pm 10%, 0.6 ohm DC res max; sim to Jeffers 4421-7K.
----- PLUGS -----		
P301 thru P311	4029840P2	Contact, electrical; sim to Amp 42827-2.
P312	4029840P3	Contact, electrical; sim to Amp 42101-2.
P313	4029840P2	Contact, electrical; sim to Amp 42827-2.
P315 thru P317	4029840P2	Contact, electrical; sim to Amp 42827-2.
P319 and P320	4029840P2	Contact, electrical; sim to Amp 42827-2.
P322	4029840P2	Contact, electrical; sim to Amp 42827-2.
P323	4029840P1	Contact, electrical; sim to Amp 41854.
P321 thru P326	4029840P2	Contact, electrical; sim to Amp 42827-2.
P327	4029840P1	Contact, electrical; sim to Amp 41854.
----- TRANSISTORS -----		
Q301* and Q302*	19A116741P1	Silicon, NPN.
		In REV A and earlier:
	19A116203P2	Silicon, NPN.
----- RESISTORS -----		
R301*	3R152P331K	Composition: 330 ohms \pm 10%, 1/4 w. Deleted by REV D.
R302	19A116278P444	Metal film: 280K ohms \pm 2%, 1/2 w.
R303	3R78P390K	Composition: 39 ohms \pm 10%, 1 w.
----- TRANSFORMERS -----		
T301	19A116041P2	Audio: 300-4000 Hz, Pri: 1.00 ohm \pm 15% DC res, Sec 1: .23 ohm \pm 15% DC res, Sec 2: 10.5 ohms \pm 15% DC res.

Technical drawing of a rectangular device, showing two views (A and B) and a detail of a component (9).

VIEW "A" (Top View): Shows the device with various components labeled 1 through 15. Component 1 is a large rectangular block on the left. Component 2 is a small rectangular block in the center. Component 3 is a small rectangular block on the right. Component 4 is a small rectangular block on the right. Component 5 is a small rectangular block on the right. Component 6 is a small rectangular block on the right. Component 7 is a small rectangular block on the right. Component 8 is a small rectangular block on the right. Component 9 is a small rectangular block on the right. Component 10 is a small rectangular block on the right. Component 11 is a small rectangular block on the right. Component 12 is a small rectangular block on the right. Component 13 is a small rectangular block on the right. Component 14 is a small rectangular block on the right. Component 15 is a small rectangular block on the right.

VIEW "B" (Bottom View): Shows the device with various components labeled 16 through 27. Component 16 is a small rectangular block on the left. Component 17 is a small rectangular block on the left. Component 18 is a small rectangular block on the left. Component 19 is a small rectangular block on the left. Component 20 is a small rectangular block on the left. Component 21 is a small rectangular block on the left. Component 22 is a small rectangular block on the left. Component 23 is a small rectangular block on the left. Component 24 is a small rectangular block on the left. Component 25 is a small rectangular block on the left. Component 26 is a small rectangular block on the left. Component 27 is a small rectangular block on the left.

DETAIL 9: A small rectangular block with a textured surface, labeled 9. It has a small rectangular block labeled 10 on its top surface. It has a small rectangular block labeled 11 on its top surface. It has a small rectangular block labeled 12 on its top surface. It has a small rectangular block labeled 13 on its top surface. It has a small rectangular block labeled 14 on its top surface. It has a small rectangular block labeled 15 on its top surface. It has a small rectangular block labeled 16 on its top surface. It has a small rectangular block labeled 17 on its top surface. It has a small rectangular block labeled 18 on its top surface. It has a small rectangular block labeled 19 on its top surface. It has a small rectangular block labeled 20 on its top surface. It has a small rectangular block labeled 21 on its top surface. It has a small rectangular block labeled 22 on its top surface. It has a small rectangular block labeled 23 on its top surface. It has a small rectangular block labeled 24 on its top surface. It has a small rectangular block labeled 25 on its top surface. It has a small rectangular block labeled 26 on its top surface. It has a small rectangular block labeled 27 on its top surface.

RC-2036

REV. A - To remove unnecessary protection. Deleted CR1.
REV. B - To incorporate new PA transistors. Changed Q301 & Q302.
REV. C - To incorporate improved design. Changed 2nd Mult Board (A303/A304).

Schematic Diagram was:

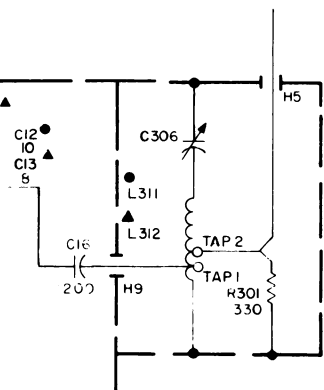
A303/A304
2ND MULT BOARD

TO J442-4
SF24 W-BL
MULTIPLIER METER

TO J442-5
SF24 W-BR-BL
MULTIPLIER 2 METER

[illegible]

. D - To improve stability of First Mixer A327/A328.
Added R4. Deleted R301 in 2nd Mult Board
A303/A304.



EV. E - Incorporate new transistor. Changed Q1.